

AMENDMENTS TO THE CLAIMS

1. **(Currently Amended)** A high-speed production method of a printed circuit board, comprising the steps of:

melting and jet-spraying a solid ink melting and jet-spraying a solid ink comprising a wax as a main component on an insulating substrate to be patterned, leaving portions corresponding to an image part unsprayed;

coating the patterned side of the insulating substrate with a conductive layer; and

removing solid ink portions by solving,

wherein the melted solid ink is jet-sprayed for patterning in accordance with data from a computer.

2. – 3. **(Cancelled)**

4. **(New)** The high-speed production method of a printed circuit board according to claim 1, wherein the solid ink has:

a melting point in a range from 50 to 100°C;

a surface tension in a range from 25 to 30 mN/m in melting condition; and

a viscosity in a range from 10 to 40 mPa•S in melting condition.

5. (New) The high-speed production method of a printed circuit board according to claim 1, wherein the solid ink is thermally melted for jet-spraying immediately before printing.

6. (New) The high-speed production method of a printed circuit board according to claim 1, further comprising the step of removing oils adhered in an offset drum process.